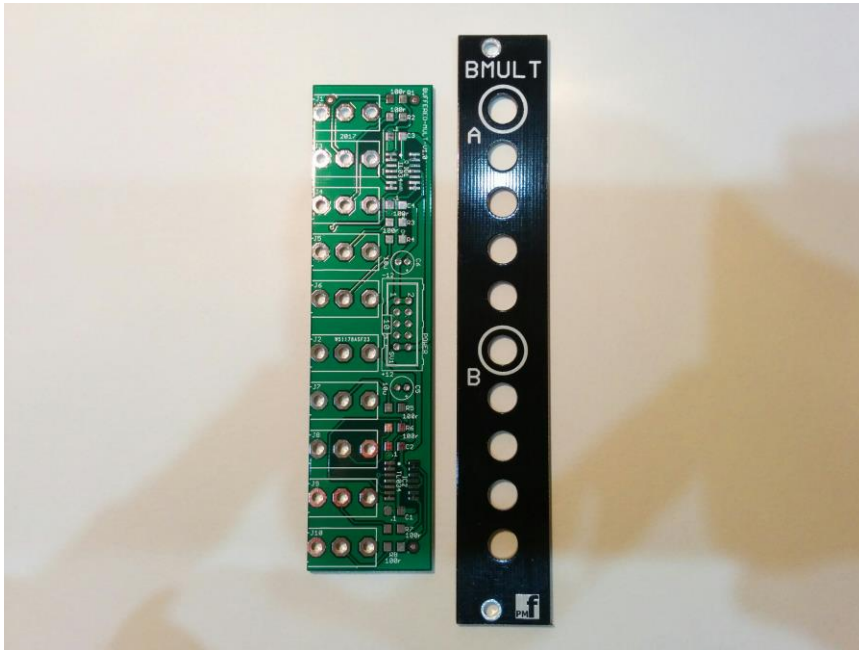


Buffered Multiple V1.0 – Assembly Guide

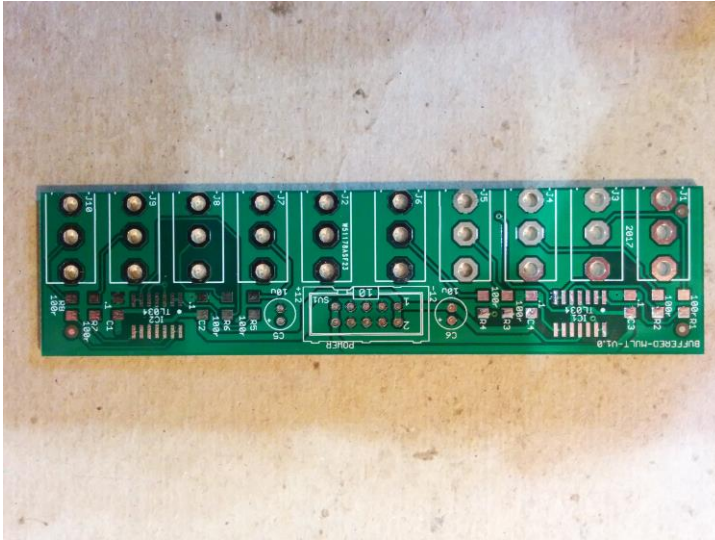
Thank you for purchasing this module! This is an easy build but with some surface mount parts including precision integrated circuits. Some of the pads are quite small and you will need a chisel tip or screwdriver tip soldering iron, fine solder and the skill to solder these tiny joints. If you have not soldered SMD before, we recommend watching some of the many YouTube guides. Our favorite: [EEVBlog](#).



The module is designed and sized for **Euro-rack** systems. You will need a 16-10 pin euro-rack power ribbon connector with $-12/0/+12$ which is connected to a synth power supply. Follow the parts lists, these instructions and the PCB silkscreen text to build the module.

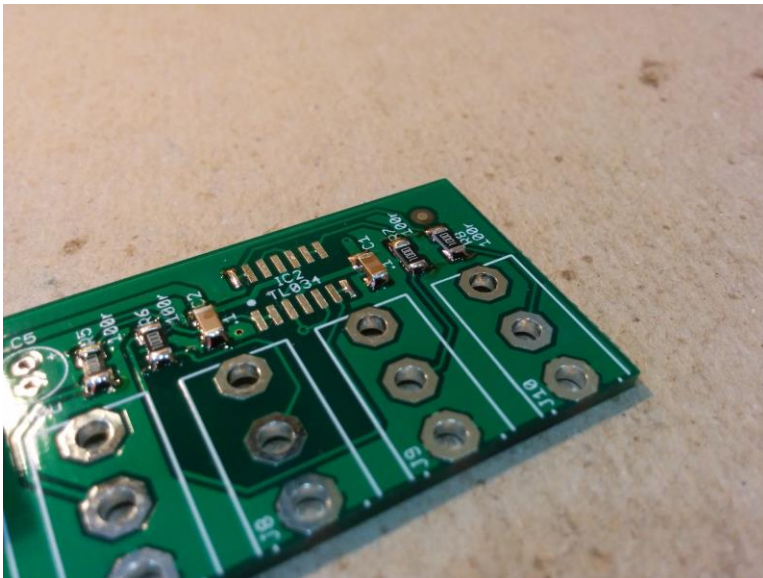
1. Board preparation

Apply flux to the SMD pads. Tin one pad of each SMD footprint with a SMALL amount of solder. For the ICs, apply a tiny amount of solder to two opposite corner pins.



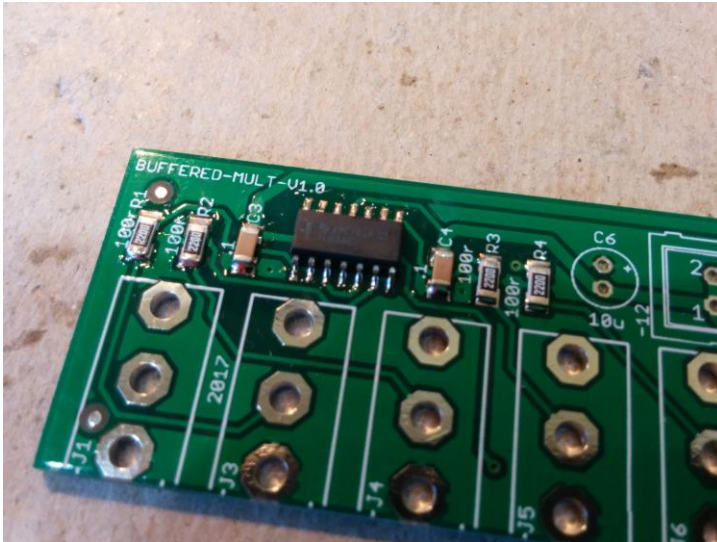
2. 1206 Size Resistors and ceramic capacitors

Install the 1206 resistors and 1206 capacitors on the TOP of the board by positioning on the footprint and heating the cap and tinned pad until the part is attached. When all 1206 parts have been attached. Solder the opposite pad of each part. Finally, reheat and add solder if necessary to finalize the first pad of each part.



3. ICs

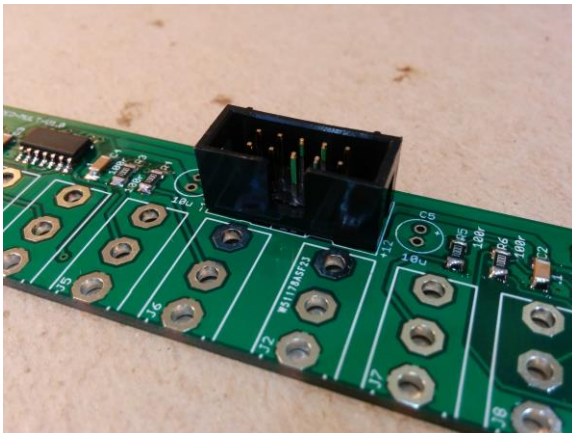
Install the ICs with the correct orientation. Align the dot/line or other marker with the corresponding mark on the board. If you solder the ICs the wrong way round, they will explode and render the board useless when power is connected. Position on the footprint and heat the pin and tinned pad in one corner until the part is attached. Position and heat the pin and tinned pad in the opposite corner until the part is attached and aligned with all pins and pads. Solder the remaining pins and pads. Finally reheat and add solder if necessary to finalize the corner pads of each part. Check for and remove any bridges between pins.



4. Power socket

Install the 10 pin power socket on the TOP of the board. **This must be installed with the correct orientation or the module will be damaged when the power is connected.**

The cut-out in the socket should face the jacks, **aligning the cut-out with the "10" marking on the board** as shown in the photo. Solder on the underside.



5. Electrolytic capacitors

These are through hole components.

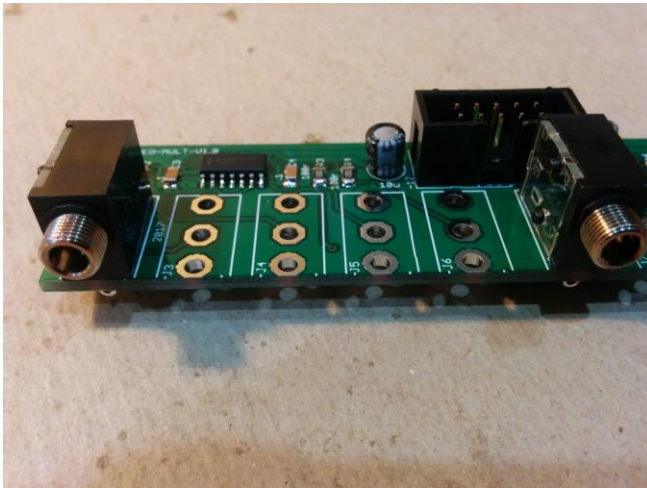
Install these on the TOP. Make sure you orient these capacitors correctly. The longer lead

and/or the lead marked with a + needs to be inserted into the hole that has the "+" marking near it. Leads marked with "-" go in the board hole WITHOUT the "+". Solder and clip the leads.



6. 3.5mm Jack Sockets

Tack one pin only with solder. These will be finalized later. Please ensure they are on the CORRECT SIDE OF THE BOARD. See Photo.



Final Assembly

1. Place the front panel over the board so that the 3.5mm jacks align with the holes in the panel.

The panel will fit either way up BUT is important that it ONLY be installed so that the panel title "BMULT" at the top of the panel is at the same end of the PCB as the label "BUFFERED-MULT" on the PCB. This ensures that the input jacks and the output jacks are in the correct place. See

photo.



2. Put nuts on the jacks and FULLY TIGHTEN all of them. Do not overtighten!
3. Now fully solder all the remaining pins on the jacks.
4. If you cut off the ends of the pins of the jacks, near to the solder joint, the module will be easier to fit into your rack close to other modules.

